

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant(s): Wayne G. Renken et al.
Title: Integrated Process Condition Sensing Wafer And Data Analysis System
Application No.: 10/718,269 Filing Date: November 19, 2003
Examiner: Unknown Group Art Unit: 2829
Docket No.: SENS.008US3 Conf. No.: 9982

Certificate of Mailing Under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 30, 2004

Signature

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant(s) call(s) the documents listed on the enclosed Form PTO-1449 to the Examiner's attention in this patent application..

This application has a filing date after June 30, 2003. Copies of the U.S. Patent(s) and U.S. Published Patent Application(s) documents listed on the accompanying Form PTO-1449 are not enclosed.

Citation of these documents shall not be construed as (1) an admission that the documents are prior art with respect to the invention or inventions claimed in this application, (2) a representation that a search has been made (other than as indicated by any cited

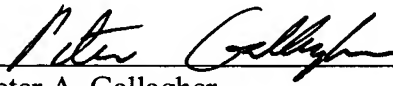
Attorney Docket No.:
SENS.008US3

Application No.:
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document), or (3) an admission that the cited information is, or is considered to be, material to patentability as defined in § 1.56(b).

This information disclosure statement is submitted under 37 C.F.R. § 1.97(b) and consequently no fee should be required. The Commissioner is authorized, however, to charge any fee that may be required, or to credit any overpayment, against Deposit Account No. 502664. This form is being submitted in duplicate.

Respectfully submitted,



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Reg. No. 47,584

June 30, 2004

Date

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U.S. Department of Commerce, Patent and Trademark	Atty. Docket No.	Application No.
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	SENS.008US3	10/718,269
	Applicant(s)	Conf. No.
(Use several sheets if necessary)	Wayne G. Renken et al.	9982
	Filing Date	Group
	November 19, 2003	2829

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	1	RE.32,369	Mar. 10, 1987	Stockton et al.			
	2	5,262,944	Nov. 16, 1993	Weisner et al.			
	3	5,435,646	Jul. 25, 1995	McArthur			
	4	5,444,637	Aug. 22, 1995	Smesny et al.			
	5	5,564,889	Oct. 15, 1996	Araki			
	6	5,969,639	Oct. 19, 1999	Lauf et al.			
	7	5,970,313	Oct. 19, 1999	Rowland et al.			
	8	6,010,538	Jan. 4, 2000	Sun et al.			
	9	6,033,922	Mar. 7, 2000	Rowland et al.			
	10	6,075,909	Jan. 13, 2000	Ressl			
	11	6,100,506	Aug. 8, 2000	Colelli, Jr. et al.			
	12	6,190,040	Feb. 20, 2001	Renken et al.			
	13	6,313,903	Nov. 6, 2001	Ogata			
	14	6,325,536	Dec. 4, 2001	Renken et al.			
	15	6,377,130	Apr. 23, 2002	Haman			
	16	6,378,378	Apr. 30, 2002	Fisher			
	17	6,472,240	Oct. 29, 2002	Akram et al.			
	18	6,542,835	Apr. 1, 2003	Mundt			
	19	6,553,277	Apr. 22, 2003	Yagisawa et al.			

U.S. Published Patent Application Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	20	2001/0014520	Aug. 16, 2001	Usui et al.			
	21	2002/0109590	Aug. 15, 2002	Parsons			
	22	2002/0161557	Oct. 31, 2002	Freed			
	23	2002/0172097	Nov. 21, 2002	Freed			
	24	2002/0177916	Nov. 28, 2002	Poolla			
	25	2002/0177917	Nov. 28, 2002	Poolla			
	26	2002/0193957	Dec. 19, 2002	Freed			

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Use separate sheets if necessary)				Wayne G. Renken et al.			9982	
				Filing Date			Group	
				November 19, 2003			2829	
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
	27	WO00/68986	Nov. 16, 2000	WIPO			Abstract	
	28	EP 1014437 A2	Jun. 28, 2000	Europe				
	29	WO02/17030A2	Feb. 28, 2002	WIPO				
	30	WO02/17030A3	Feb. 28, 2002	WIPO				
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
	31	Prov. Pat. App. No. 60/285,613 filed 4/19/01; Freed et al.; "Firmware, Methods, Apparatus, and Computer Program Products for Wafer Sensors"						
	32	Prov. Pat. App. No. 60/285,439 filed 4/19/01; Freed et al.; "Methods Apparatus, and Computer Program Products for Obtaining Data for Process Operation, Optimization, Monitoring, and Control"						
	33	Freed et al.; "Autonomous On-Wafer Sensors for Process Modeling, Diagnosis, and Control," IEEE Transactions on Semiconductor Manufacturing, Vol. 14, no. 3, Aug. 2001, pp 255-264.						
	34	Freed; "Wafer-Mounted Sensor Arrays for Plasma Etch Processes", Dissertation, Univ. of CA. Berkeley, Fall 2001						
	35	Baker et al.; "A Novel In Situ Monitoring Technique for Reactive Ion Etching Using a Surface Micromachined Sensor," IEEE Transactions on Semiconductor Manufacturing, Vol. 11, No. 2, May 1998, pp. 254-64.						
Examiner			Date Considered					
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.</p>								

